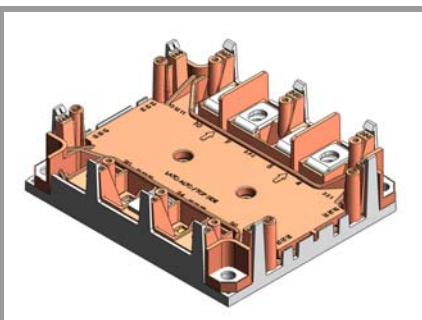


SKiM301TMLI12E4C



SKiM® 4

Trench IGBT Modules

SKiM301TMLI12E4C

Features

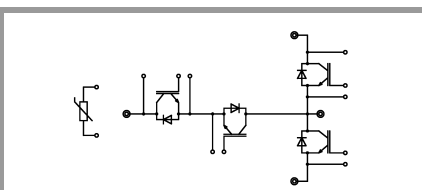
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Typical Applications*

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- High reliability AC inverter wind
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Remarks

- Case temperature limited to $T_s = 125^\circ C$ max; $T_c = T_s$ (for baseplateless modules)
- Recommended $T_{op} = -40 \dots +150^\circ C$



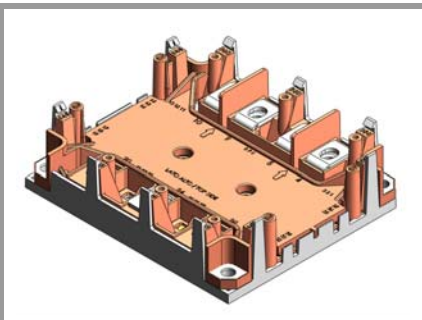
TMLI

Absolute Maximum Ratings			
Symbol	Conditions	Values	Unit
IGBT 1			
V_{CES}	$T_j = 25^\circ C$	1200	V
I_C	$T_j = 150^\circ C$	$T_s = 25^\circ C$	263
		$T_s = 70^\circ C$	200
I_C	$T_j = 175^\circ C$	$T_s = 25^\circ C$	294
		$T_s = 70^\circ C$	237
I_{Cnom}		300	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	900	A
V_{GES}		-20 ... 20	V
t_{psc}	$V_{CC} = 800 V$ $V_{GE} \leq 15 V$ $V_{CES} \leq 1200 V$	$T_j = 150^\circ C$	10
T_j		-40 ... 175	$^\circ C$

Absolute Maximum Ratings			
Symbol	Conditions	Values	Unit
IGBT 2			
V_{CES}	$T_j = 25^\circ C$	1200	V
I_C	$T_j = 150^\circ C$	$T_s = 25^\circ C$	263
		$T_s = 70^\circ C$	200
I_C	$T_j = 175^\circ C$	$T_s = 25^\circ C$	294
		$T_s = 70^\circ C$	237
I_{Cnom}		300	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	900	A
V_{GES}		-20 ... 20	V
t_{psc}	$V_{CC} = 800 V$ $V_{GE} \leq 15 V$ $V_{CES} \leq 1200 V$	$T_j = 150^\circ C$	10
T_j		-40 ... 175	$^\circ C$

Absolute Maximum Ratings			
Symbol	Conditions	Values	Unit
Module			
$I_{t(RMS)}$	$T_{terminal} = 80^\circ C,$	400	A
T_{stg}		-40 ... 125	$^\circ C$
V_{isol}	AC sinus 50 Hz, $t = 1 \text{ min}$	2500	V

SKiM301TMLI12E4C



SKiM® 4

Trench IGBT Modules

SKiM301TMLI12E4C

Features

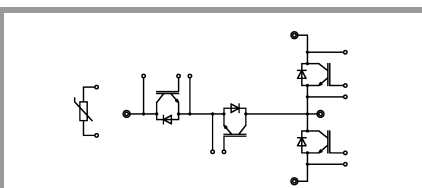
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Remarks

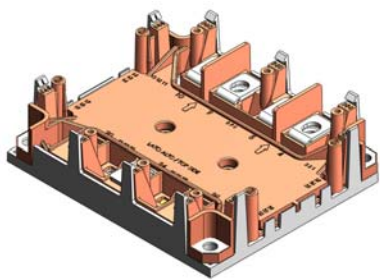
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TMLI

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Diode 1				
V_{RRM}	$T_j = 25^\circ C$		1200	V
I_F	$T_j = 175^\circ C$	$T_s = 25^\circ C$	274	A
		$T_s = 70^\circ C$	217	A
I_F	$T_j = 175^\circ C$	$T_s = 25^\circ C$	274	A
		$T_s = 70^\circ C$	217	A
I_{Fnom}			300	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		900	A
I_{FSM}	10 ms, sin 180° , $T_j = 150^\circ C$		1485	A
T_j			-40 ... 175	$^\circ C$

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Diode 2				
V_{RRM}	$T_j = 25^\circ C$		1200	V
I_F	$T_j = 175^\circ C$	$T_s = 25^\circ C$	274	A
		$T_s = 70^\circ C$	217	A
I_F	$T_j = 175^\circ C$	$T_s = 25^\circ C$	274	A
		$T_s = 70^\circ C$	217	A
I_{Fnom}			300	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		900	A
I_{FSM}	10 ms sin 180°	$T_j = 25^\circ C$	1485	A
		$T_j = 150^\circ C$	1485	A
T_j			-40 ... 175	$^\circ C$



SKiM® 4

Trench IGBT Modules

SKiM301TMLI12E4C

Features

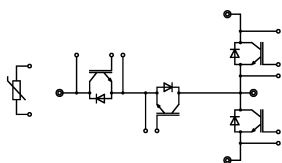
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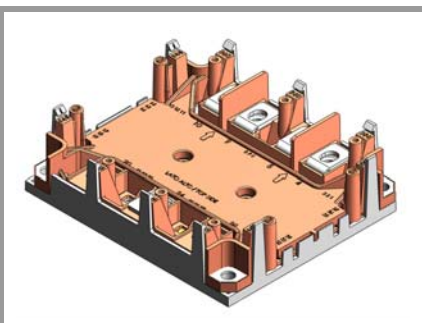
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- Recommended $T_{op} = -40 \dots +150^\circ C$



TMI

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT 1						
$V_{CE(sat)}$	$I_C = 300 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipllevel	$T_j = 25^\circ C$		1.80	2.05	V
		$T_j = 150^\circ C$		2.20	2.40	V
V_{CE0}	chipllevel	$T_j = 25^\circ C$		0.8	0.9	V
		$T_j = 150^\circ C$		0.7	0.8	V
r_{CE}	$V_{GE} = 15 \text{ V}$ chipllevel	$T_j = 25^\circ C$		3.3	3.8	m Ω
		$T_j = 150^\circ C$		5.0	5.3	m Ω
$V_{GE(th)}$	$V_{GE} = V_{CE} \text{ V}, I_C = 11.4 \text{ mA}$		5	5.8	6.5	V
I_{CES}	$V_{GE} = 0 \text{ V}$ $V_{CE} = 1200 \text{ V}$	$T_j = 25^\circ C$				mA
						mA
C_{ies}	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$		18.45		nF
C_{oes}		$f = 1 \text{ MHz}$		1.215		nF
C_{res}		$f = 1 \text{ MHz}$		1.035		nF
Q_G	$-8 \text{ V} \dots +15 \text{ V}$			1695		nC
R_{Gint}	$T_j = 25^\circ C$			2.50		Ω
$t_{d(on)}$	$V_{CE} = 3 \text{ V}$	$T_j = 150^\circ C$		217.9		ns
t_r	$I_C = 300 \text{ A}$	$T_j = 150^\circ C$		69.43		ns
E_{on}	$R_{G on} = 2.7 \Omega$ $R_{G off} = 2.7 \Omega$	$T_j = 150^\circ C$		6.619		mJ
$t_{d(off)}$	$di/dt_{on} = 5626 \text{ A}/\mu\text{s}$	$T_j = 150^\circ C$		355.5		ns
t_f	$di/dt_{off} = 2636 \text{ A}/\mu\text{s}$	$T_j = 150^\circ C$		91.3		ns
E_{off}	$V_{GE neg} = -15 \text{ V}$ $V_{GE pos} = 15 \text{ V}$	$T_j = 150^\circ C$		19.376		mJ
$R_{th(j-s)}$	per IGBT			0.21		K/W

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT 2						
$V_{CE(sat)}$	$I_C = 300 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipllevel	$T_j = 25^\circ C$		1.8	2.05	V
		$T_j = 150^\circ C$		2.2	2.4	V
V_{CE0}	chipllevel	$T_j = 25^\circ C$		0.8	0.9	V
		$T_j = 150^\circ C$		0.7	0.8	V
r_{CE}	$V_{GE} = 15 \text{ V}$ chipllevel	$T_j = 25^\circ C$		3.3	3.8	m Ω
		$T_j = 150^\circ C$		5.0	5.3	m Ω
$V_{GE(th)}$	$V_{GE} = V_{CE} \text{ V}, I_C = 11.4 \text{ mA}$		5	5.8	6.5	V
I_{CES}	$V_{GE} = 0 \text{ V}$ $V_{CE} = 1200 \text{ V}$	$T_j = 25^\circ C$				mA
		$T_j = 150^\circ C$				mA
C_{ies}	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$		18.45		nF
C_{oes}		$f = 1 \text{ MHz}$		1.215		nF
C_{res}		$f = 1 \text{ MHz}$		1.035		nF
Q_G	$-8 \text{ V} \dots +15 \text{ V}$			1695		nC
R_{Gint}	$T_j = 25^\circ C$			2.50		Ω
$t_{d(on)}$	$V_{CE} = 300 \text{ V}$	$T_j = 150^\circ C$		217.9		ns
t_r	$I_C = 300 \text{ A}$	$T_j = 150^\circ C$		69.43		ns
E_{on}	$R_{G on} = 2.7 \Omega$ $R_{G off} = 2.7 \Omega$	$T_j = 150^\circ C$		6.619		mJ
$t_{d(off)}$	$di/dt_{on} = 5626 \text{ A}/\mu\text{s}$	$T_j = 150^\circ C$		355.5		ns
t_f	$di/dt_{off} = 2336 \text{ A}/\mu\text{s}$	$T_j = 150^\circ C$		91.3		ns
E_{off}	$V_{GE neg} = -15 \text{ V}$ $V_{GE pos} = 15 \text{ V}$	$T_j = 150^\circ C$		19.376		mJ
$R_{th(j-s)}$	per IGBT			0.21		K/W



SKiM® 4

Trench IGBT Modules

SKiM301TMLI12E4C

Features

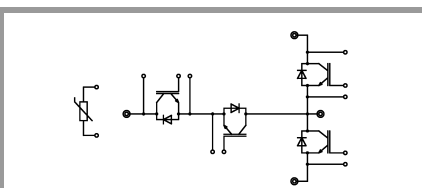
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Typical Applications*

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Remarks

- Case temperature limited to $T_s = 125^\circ C$ max; $T_C = T_s$ (for baseplateless modules)
- Recommended $T_{op} = -40 \dots +150^\circ C$

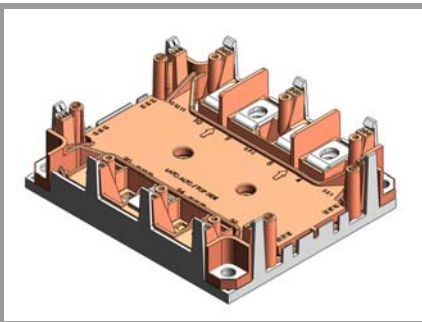


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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Diode 1						
$V_F = V_{EC}$	$I_F = 300\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ C$		2.20	2.52	V
		$T_j = 150^\circ C$		2.15	2.47	V
V_{F0}	chipelevel	$T_j = 25^\circ C$	1.1	1.3	1.5	V
		$T_j = 150^\circ C$	0.7	0.9	1.1	V
r_F	chipelevel	$T_j = 25^\circ C$	2.7	3.0	3.4	m Ω
		$T_j = 150^\circ C$	3.5	4.2	4.6	m Ω
I_{RRM}	$I_F = 300\text{ A}$	$T_j = 150^\circ C$		132.43		A
Q_{rr}		$T_j = 150^\circ C$		21.47		μC
E_{rr}	$V_R = 300\text{ V}$	$T_j = 150^\circ C$		1.79		mJ
$R_{th(j-s)}$	per DIODE			0.25		K/W

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Diode 2						
$V_F = V_{EC}$	$I_F = 300\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ C$		2.2	2.50	V
		$T_j = 150^\circ C$		2.15	2.47	V
V_{F0}	chipelevel	$T_j = 25^\circ C$	1.1	1.3	1.5	V
		$T_j = 150^\circ C$	0.7	0.9	1.1	V
r_F	chipelevel	$T_j = 25^\circ C$	2.7	3.0	3.4	m Ω
		$T_j = 150^\circ C$	3.5	4.2	4.6	m Ω
I_{RRM}	$I_F = 300\text{ A}$	$T_j = 150^\circ C$		132.43		A
Q_{rr}		$T_j = 150^\circ C$		21.47		μC
E_{rr}	$V_R = 300\text{ V}$	$T_j = 150^\circ C$		1.79		mJ
$R_{th(j-s)}$	per DIODE			0.25		K/W

SKiM301TMLI12E4C



SKiM® 4

Trench IGBT Modules

SKiM301TMLI12E4C

Features

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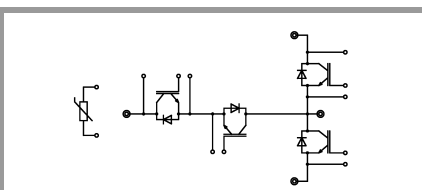
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- Recommended $T_{op} = -40 \dots +150^\circ C$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Module						
L_{CE}				18		nH
$R_{CC'+EE'}$	terminal-chip	$T_s = 25^\circ C$		1.35		m Ω
		$T_s = 125^\circ C$		1.75		m Ω
$R_{th(c-s)}$	per module					K/W
M_s	to heat sink (M5)		2		3	Nm
M_t		to terminals M6	4		5	Nm
						Nm
w				317		g



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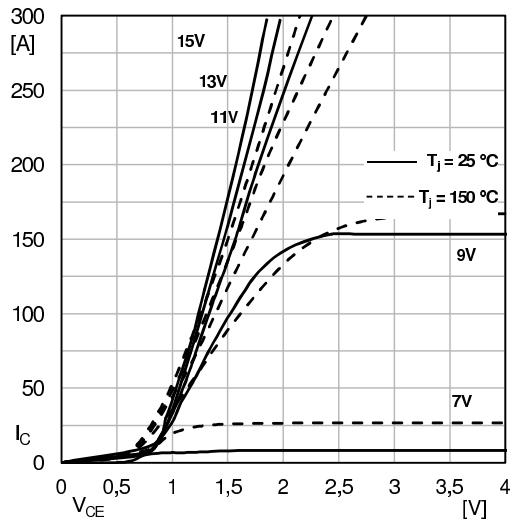


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

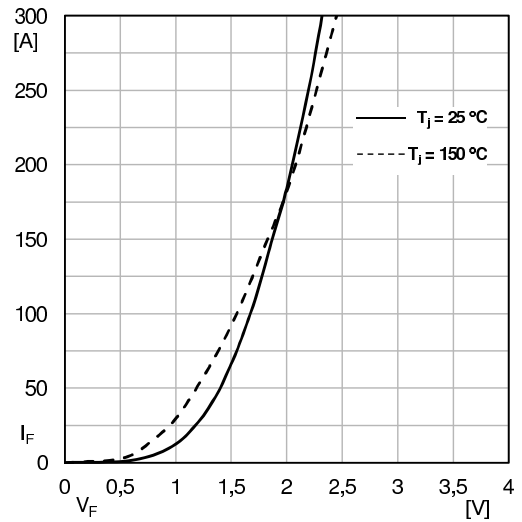


Fig. 2: Typ. Diode 1 output characteristics

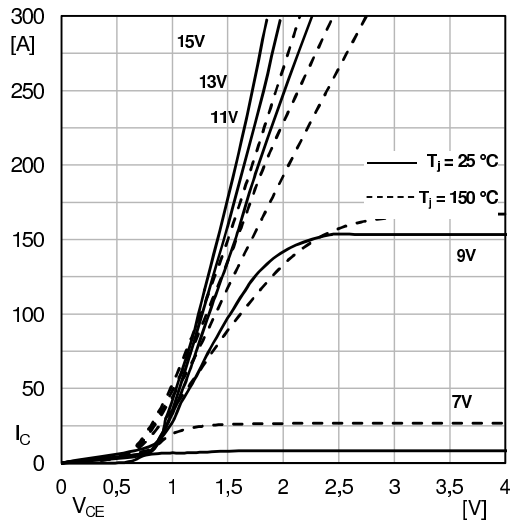


Fig. 3: Typ. IGBT 2 output characteristic, inclusive $R_{CC'+EE'}$

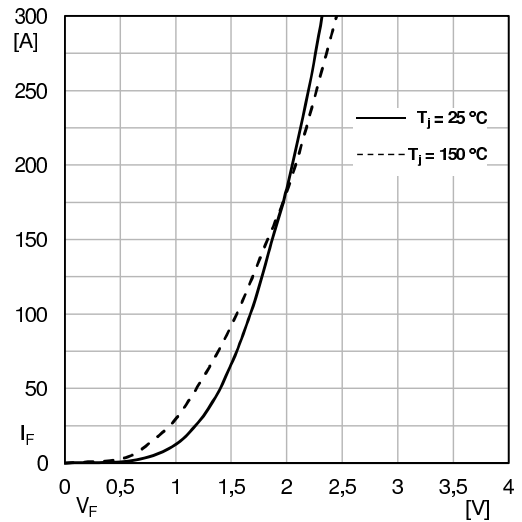


Fig. 4: Typ. Diode 2 output characteristic

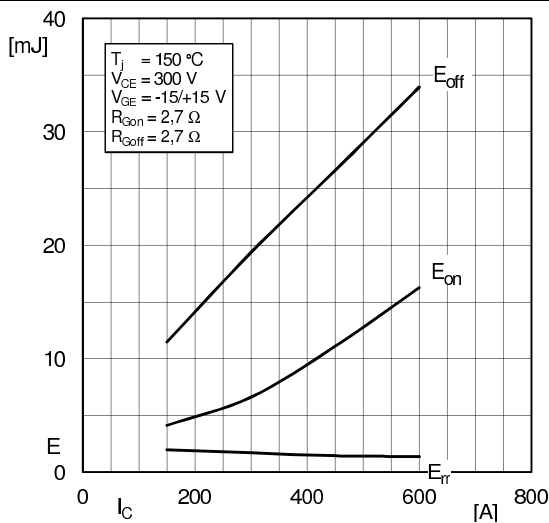


Fig. 5: Typ. IGBT 1 turn-on /-off energy = $f(I_c)$

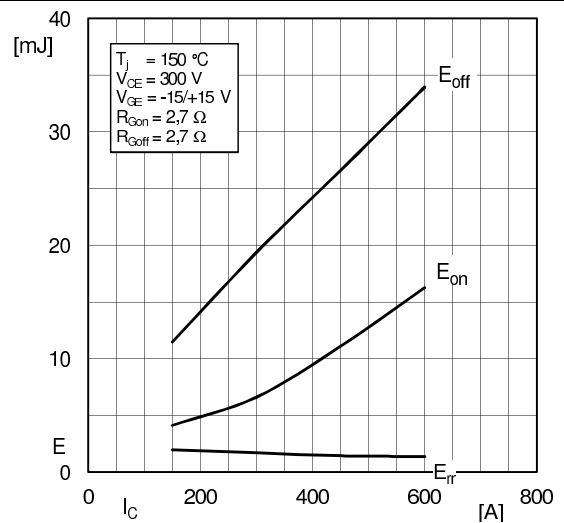


Fig. 6: Typ. IGBT 2 turn-on /-off energy = $f(I_c)$

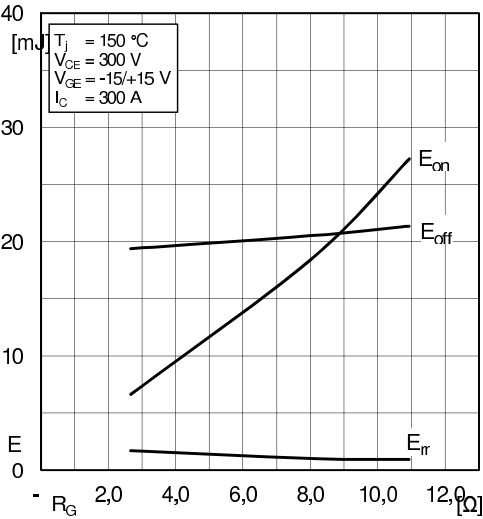


Fig. 7: Typ. IGBT 1 turn-on /-off energy = f (R_G)

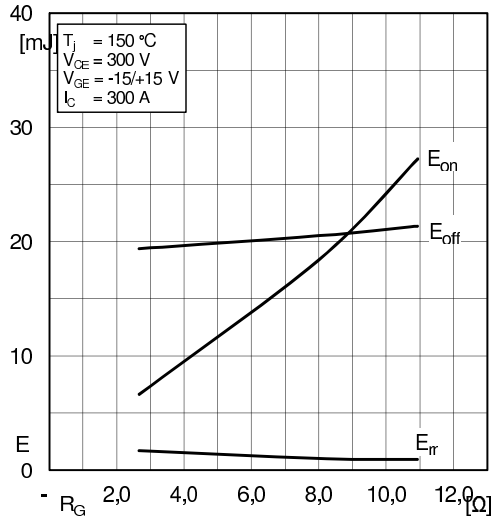


Fig. 8: Typ. IGBT 2 turn-on /-off energy = f (R_G)

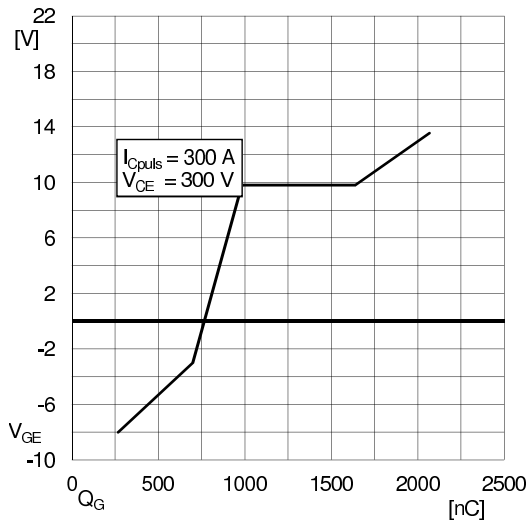


Fig. 9: Typ. IGBT 1 gate charge characteristic

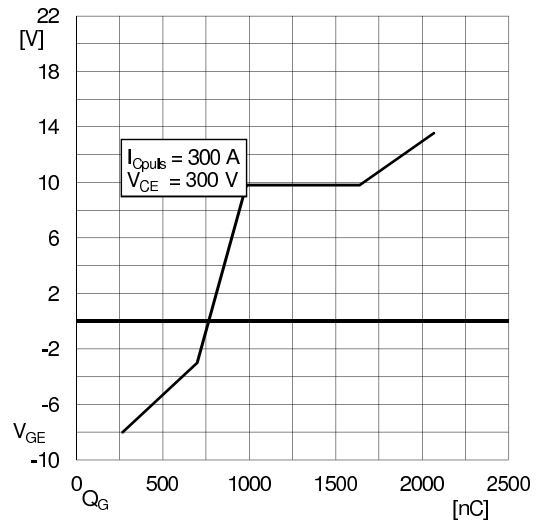


Fig. 10: Typ. IGBT 2 gate charge characteristic

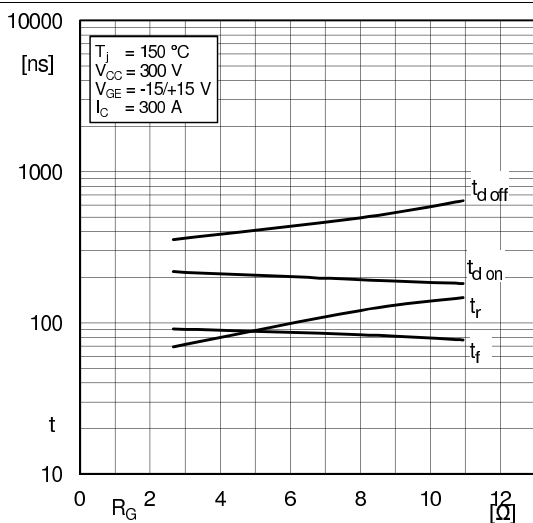


Fig. 11: Typ. IGBT 1 switching times vs. gate resistor R_G

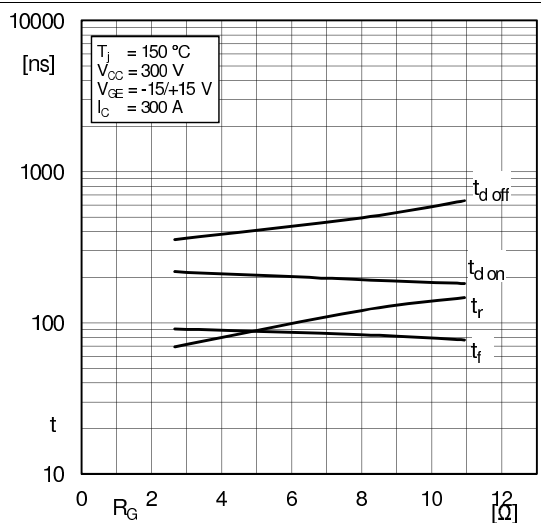


Fig. 12: Typ. IGBT 2 switching times vs. gate resistor R_G

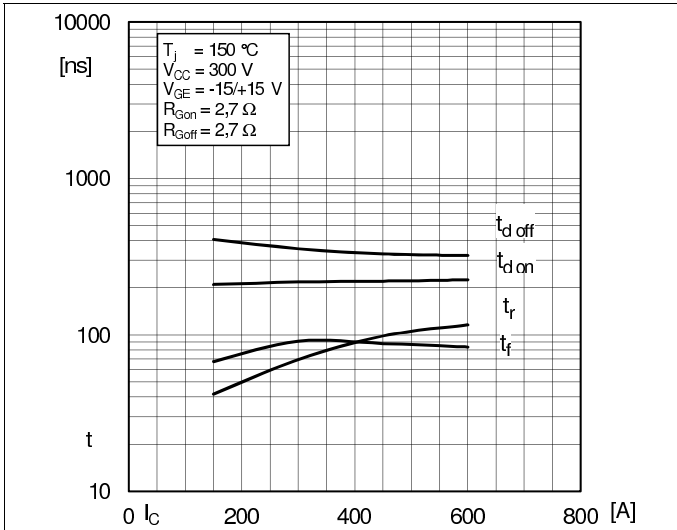


Fig. 13: Typ. IGBT 1 switching times vs. I_C

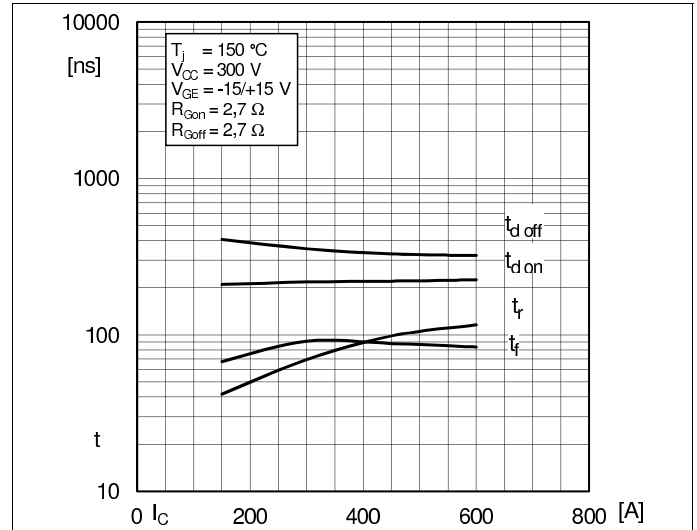


Fig. 14: Typ. IGBT 2 switching times vs. I_C

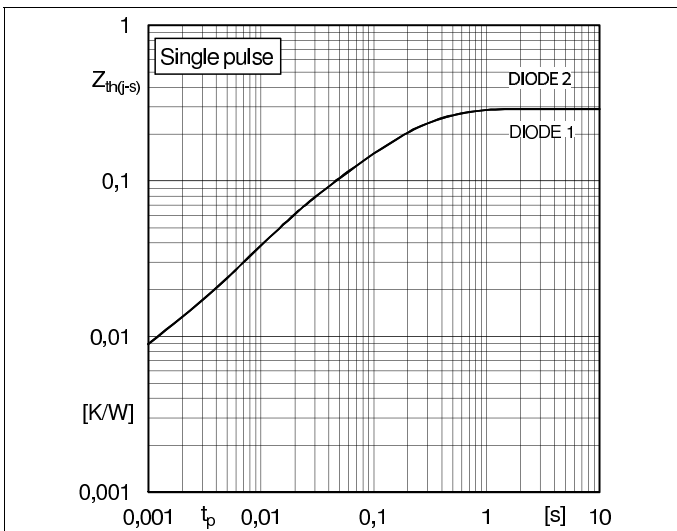


Fig. 15: Typ. DIODEs transient thermal impedance

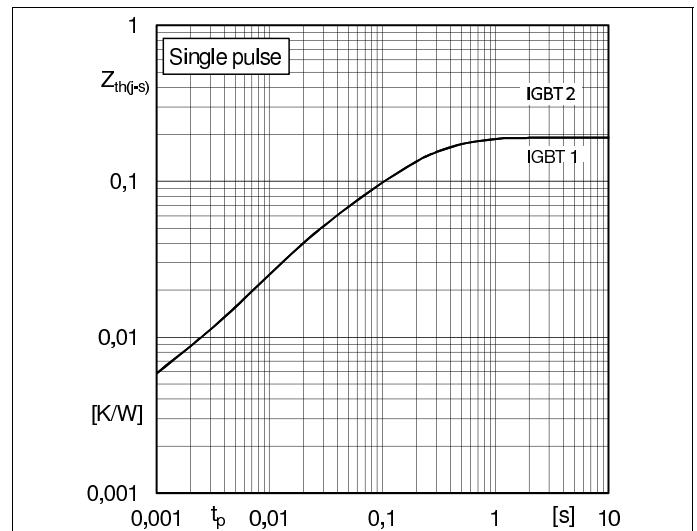
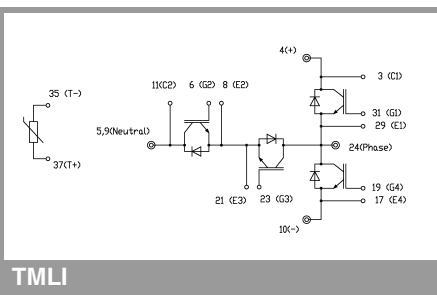
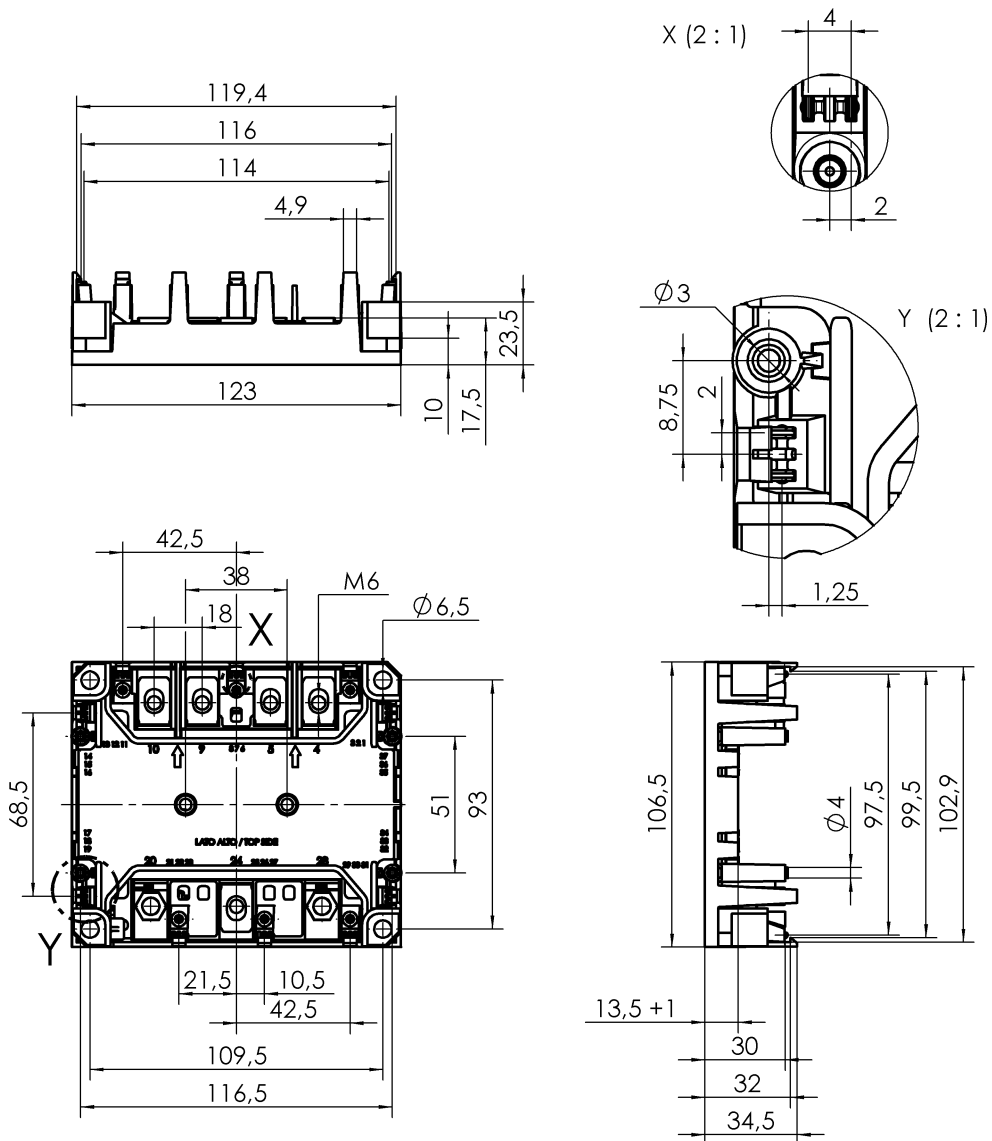


Fig. 16: Typ. IGBTs transient thermal impedance

SKiM301TMLI12E4C



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.